



Sheet 1 of 1

Form 1449*

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INFORMATION DISCLOSURE STATEMENT
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(Use several sheets if necessary)

Applicant: Leonard Forbes et al.

Filing Date: May 26, 1999

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U. S. PATENT DOCUMENTS

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FOREIGN PATENT DOCUMENTS

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OTHER DOCUMENTS

(Including Author, Title, Date, Pertinent Pages, Etc.)

| | |
|-----------|---|
| <i>QJ</i> | Denton, J.P., et al., "Fully Depleted Dual-Gated Thin-Film SOI P-MOSFET's Fabricated in SOI Islands with an Isolated Buried Polysilicon Backgate", <u>IEEE Electron Device Letters</u> , 17(11), pp. 509-511, (November 1996) |
| <i>QJ</i> | Frank, D.J., et al., "Monte Carlo Simulation of a 30 nm Dual-Gate MOSFET: How Short Can Si Go?", <u>IEDM</u> , pp. 553-556, (1992) |
| <i>QJ</i> | Frank, J., et al., "Monte Carlo Simulations of p- and n-Channel Dual-Gate Si MOSFET's at the Limits of Scaling", <u>IEEE Transactions on Electron Devices</u> , 40(11), pg. 2103, (November 1993) |
| <i>QJ</i> | Mizuno, T., et al., "High Performance Characteristics in Trench Dual-Gate MOSFET (TDMOS)", <u>IEEE Transactions on Electron Devices</u> , 38(9), pp. 2121-2127, (1991) |

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*Substitute Disclosure Statement Form (PTO-1449)

Date Considered

2/11/02

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